Final Product/Process Change Notification

Document #:FPCN21372XB
Issue Date: 05 May 2022

Title of Change:	Wafer fab transfer to onsemi Fab10 Pocatello Idaho, United States from Fab2 Oudenaarde, Belgium related to Fab2 sale and assembly location transfer to UTAC, Thailand from onsemi Seremban, Malaysia.
Proposed First Ship date:	12 Aug 2022 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Kevin.VanHyfte@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Jim.Workman@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Traceability guaranteed by datecode
Change Category:	Assembly Change, Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Pocatello Idaho, United States	UTAC, Thailand

Description and Purpose:

Wafer fab transfer to onsemi Fab10 Pocatello Idaho, United States from onsemi Fab2 Oudenaarde, Belgium related to Fab2 sale. Assembly location transfer to UTAC, Thailand from onsemi Seremban, Malaysia.

Subject to a commercial agreement, onsemi may extend the deliveries outside the First Ship Date which is the proposed date of implementation.

	From	**To**
Fab Site	Fab2, Oudenaarde, Belgium (Current Fab)	Fab10, Pocatello, Idaho, USA (New Fab)
Wafer size	Substrate: Si (150mm) 6”	Substrate: Si (200mm) 8"

	From	**To**
Assembly Site	onsemi Seremban, Malaysia (Current Site)	UTAC, Thailand (New Site)
Die Attach	CRM-1084P conductive	Abletherm 8600 conductive
Mold Compound	G760	G700L type TD

There are no product material changes as a result of this change.

There is no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME NCP1090DRG
PACKAGE 8 SOIC150

Test	Specification	Condition	Interval	Results
HBM	JESD22-A114	0k5V, 1kV, 1k5V,2kV, 2k5V, 3kV	2kV	0/18
MM	JESD22-A115	50V, 100V, 150V, 200V	200V	0/12
CDM	JESD22-C101	250V, 500V, 750V	500V	0/9
LU	JESD78	+/- 100 mA, O.V. 57V, Ta = 85°C	100mA	0/6

QV DEVICE NAME NCP1093MNRG
PACKAGE 10 DFN

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 3, 3x IR @ 260C °C, Pre TC, uHAST	3x IR	0/462

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
NCP1094MNRG	NCP1090DRG, NCP1093MNRG
NCP1093MNRG	NCP1090DRG, NCP1093MNRG
NCP1093MNG	NCP1090DRG, NCP1093MNRG

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCP1094MNRG	0HINT-008-XTP	NCP1090DRG, NCP1093MNRG		
NCP1093MNRG	0HINT-007-XTP	NCP1090DRG, NCP1093MNRG		